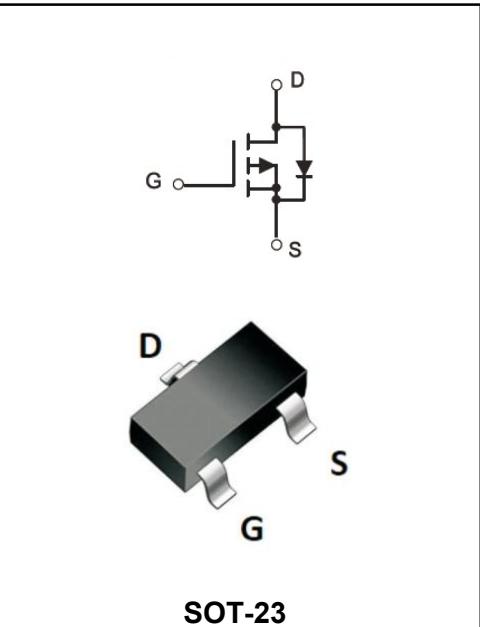


## -12V P-CHANNEL ENHANCEMENT MODE MOSFET

## MAIN CHARACTERISTICS

$I_D$	-4.8A
$V_{DSS}$	-12V
$R_{DS(on)-typ}(@V_{GS}=-4.5V)$	< 32mΩ (Type: 26 mΩ)



## Application

- electronic cigarette
- Load switch

## Marking Code

YFW2311B	2311B
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Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	-12	V
Gate - Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=25^\circ\text{C}$	$I_D$	-4.8	A
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=100^\circ\text{C}$	$I_D$	-2.6	A
Pulsed Drain Current <sup>note1</sup>	$I_{DM}$	-16	A
Power Dissipation @ $T_c=25^\circ\text{C}$	$P_D$	1	W
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	125	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

Maximum Ratings at  $T_c=25^\circ C$  unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	$V(BR)DSS$	-12	-18	-	V
Zero Gate Voltage Drain Current	$V_{DS}=-12V, V_{GS}=0V$	$I_{DSS}$	-	-	-1	$\mu A$
Gate to Body Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	$I_{GSS}$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	$V_{GS(th)}$	-0.4	-0.65	-1.0	V
Static Drain-Source on-Resistance note2	$V_{GS}=-4.5V, I_D=-4.1A$	$R_{DS(ON)}$	-	26	32	$m\Omega$
	$V_{GS}=-2.5V, I_D=-3A$		-	35	53	
Input Capacitance	$V_{DS}=-4V$ $V_{GS}=0V$ $f=1MHz$	$C_{iss}$	-	905	-	pF
Output Capacitance		$C_{oss}$	-	210	-	
Reverse Transfer Capacitance		$C_{rss}$	-	195	-	
Total Gate Charge	$V_{DS}=-4V$ $I_D=-4.1A$ $V_{GS}=-4.5V$	$Q_g$	-	7.8	15	nC
Gate-Source Charge		$Q_{gs}$	-	1.2	-	
Gate-Drain("Miller") Charge		$Q_{gd}$	-	1.6	-	
Turn-on delay time	$V_{DD}=-4V$ $I_D=-3.3A$ $R_G=1.0\Omega$ $V_{GEN}=-4.5V$ $R_L=1.2\Omega$	$t_{d(on)}$	-	13	20	ns
Turn-on Rise Time		$T_r$	-	35	53	
Turn-Off Delay Time		$t_{d(OFF)}$	-	32	48	
Turn-Off Fall Time		$t_f$	-	10	20	
Maximum Continuous Drain to Source Diode Forward Current		$I_s$	-	-	-4.1	A
Maximum Pulsed Drain to Source Diode Forward Current		$I_{SM}$	-	-	-16	A
Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_s=-4.1A$	$V_{SD}$	-	-	-1.2	V
Reverse Recovery Time	$I_s=-4.1A, dI/dt=100A/\mu s$ , $V_{GS}=0V$	$t_{rr}$	-	20	-	ns
Reverse Recovery Charge		$Q_{rr}$	-	9	-	nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
3. The power dissipation is limited by  $150^\circ C$  junction temperature
4. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

### Ratings and Characteristic Curves

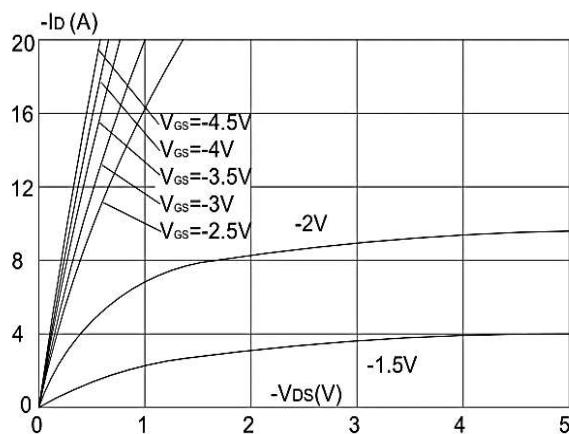


Figure 1: Output Characteristics

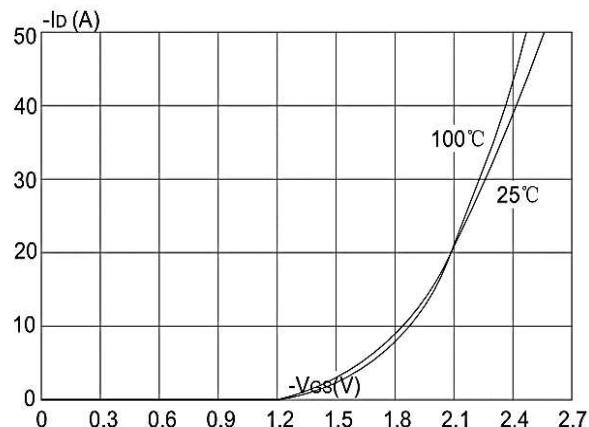


Figure 2: Typical Transfer Characteristics

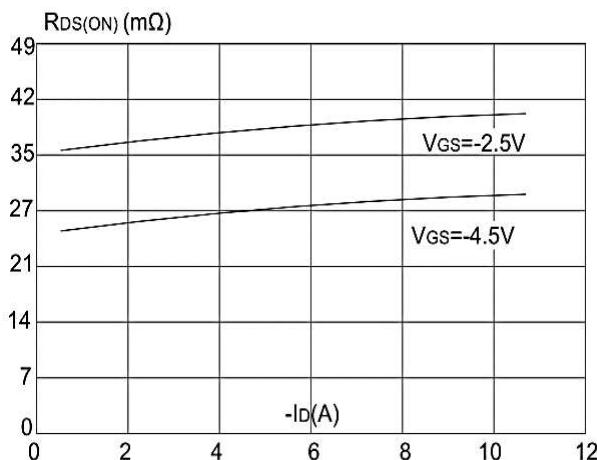


Figure 3: On-resistance vs. Drain Current

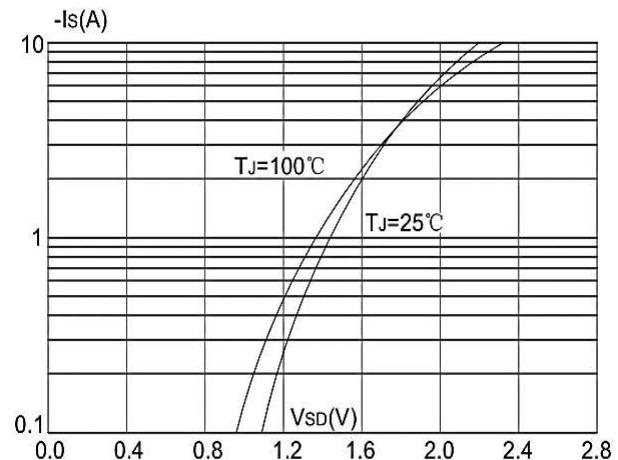


Figure 4: Body Diode Characteristics

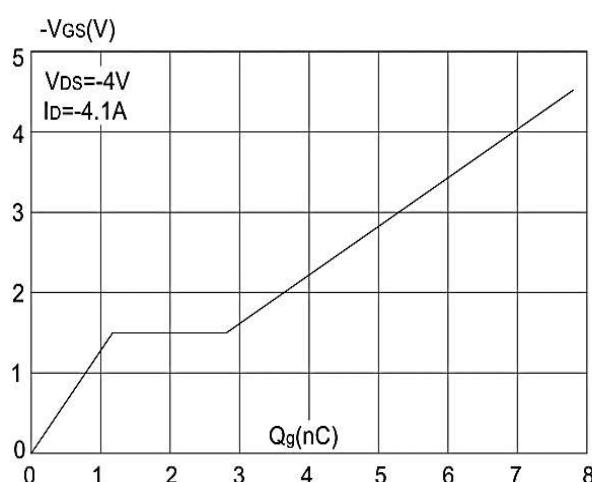


Figure 5: Gate Charge Characteristics

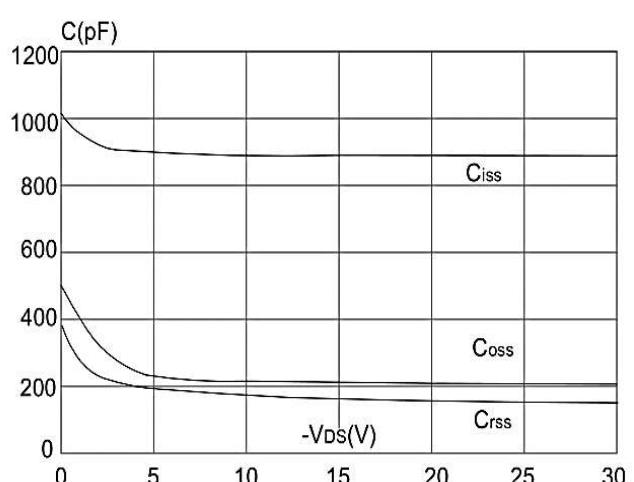
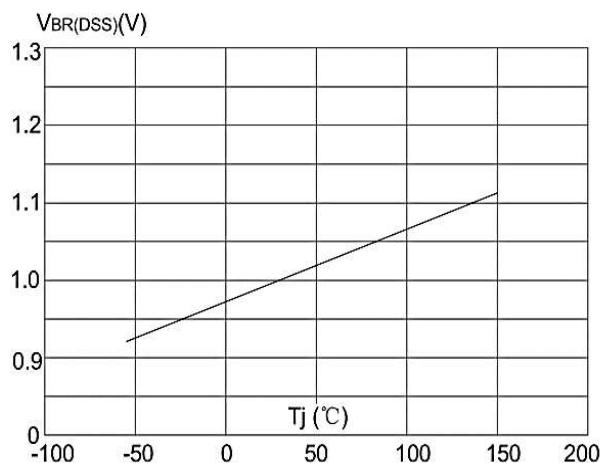
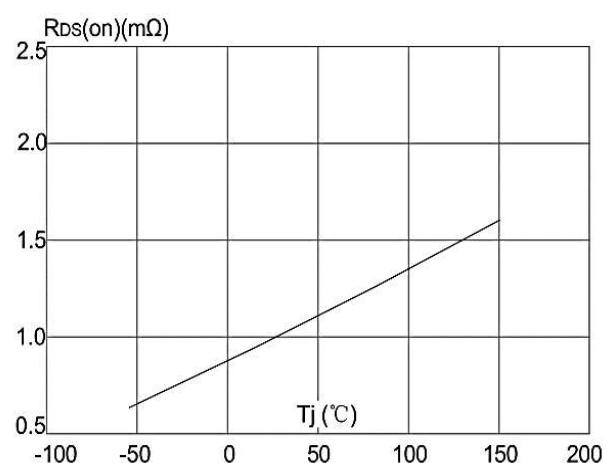


Figure 6: Capacitance Characteristics

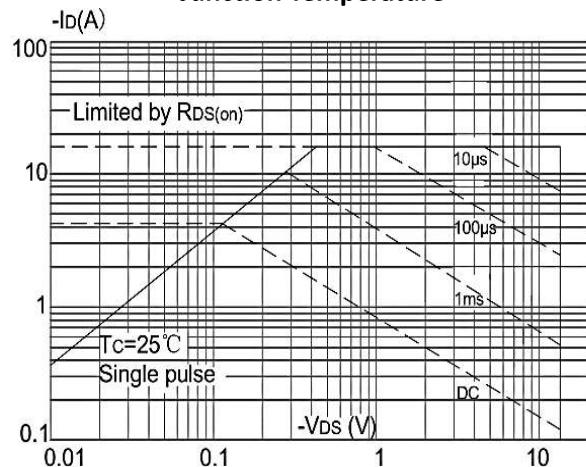
### Ratings and Characteristic Curves



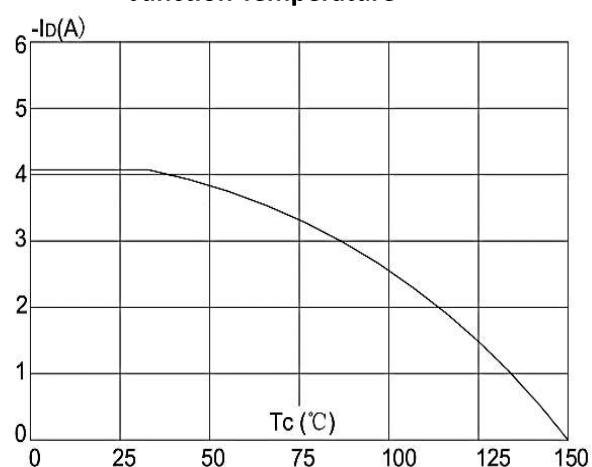
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



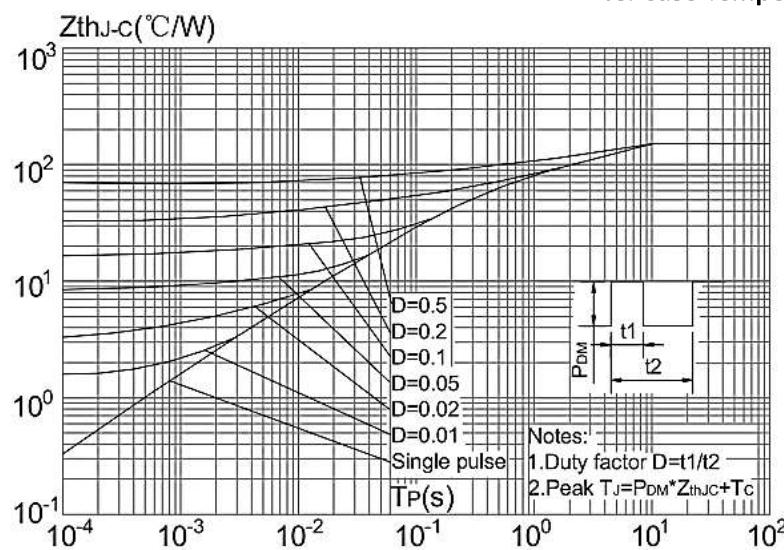
**Figure 8: Normalized on Resistance vs. Junction Temperature**



**Figure 9: Maximum Safe Operating Area**



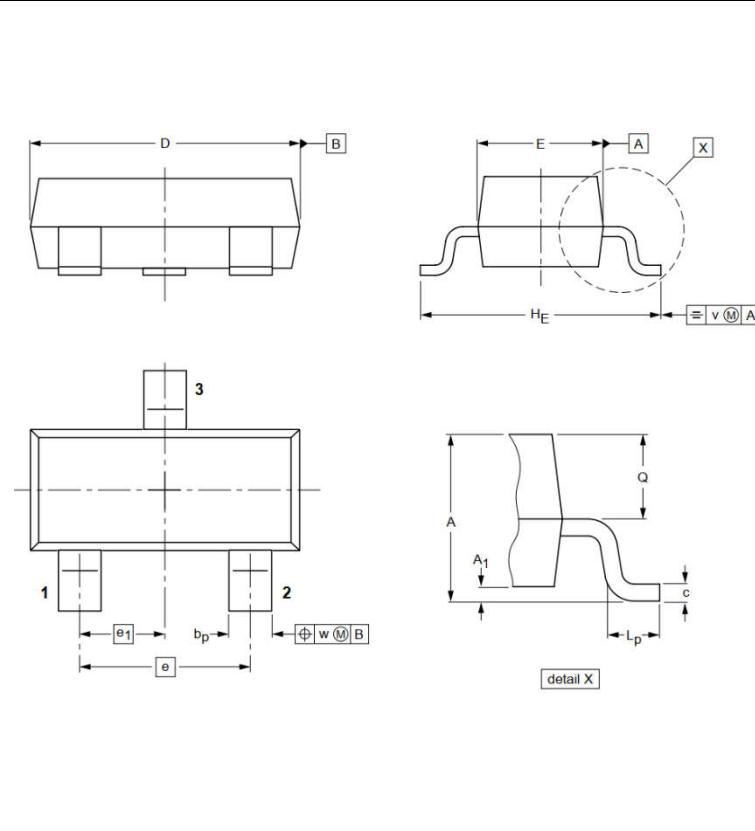
**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



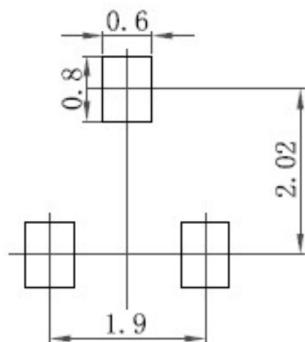
**Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case**

**Ordering information**

Package	Packing Description	Base Quantity	Packing Quantity
SOT-23	Tape/Reel,7"reel	3000pcs/Reel	24000PCS/Box 120000PCS/Carton

**Package Dimensions**
**SOT-23**


Dim.	Millimeter (mm)		mil	
	Min.	Max.	Min.	Max.
A	0.9	1.15	35	45
A1	0.1		3.9	
bp	0.38	0.48	15	19
C	0.09	0.15	3.54	5.9
D	2.8	3.0	110	118
E	1.2	1.4	47	55
E	1.9		75	
E1	0.95		37	
HE	2.1	2.55	83	100
Lp	0.15	0.45	5.9	18
Q	0.45	0.55	18	22
V	0.2		7.9	
W	0.1		4	

**The recommended mounting pad size**


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